

RD Number: RD119

RD Title: TB67S105FTG Evaluation Circuit BOM

| Item No. | Designator | Quantity | Value | Part Number | Manufacturer | Description | Package | Not Mount |
|----------|------------|----------|----------------|-------------|--------------|------------------------|--------------|-----------|
| 1 | C_VCC | 1 | 0.1μF 25V | — | — | Chip capacitor | 3.2mm×1.6mm | |
| 2 | C_VM2 | 1 | 0.1μF 50V | — | — | Chip capacitor | 3.2mm×1.6mm | |
| 3 | C_VRFA | 1 | 0.1μF 25V | — | — | Chip capacitor | 3.2mm×1.6mm | |
| 4 | C_VRFB | 1 | 0.1μF 25V | — | — | Chip capacitor | 3.2mm×1.6mm | |
| 5 | C_VM1 | 1 | 100μF 50V | — | — | Electrolytic capacitor | | |
| 6 | C_VDD | 1 | 10μF 25V | — | — | Electrolytic capacitor | | |
| 7 | C_OSCM | 0 | Socket pin | — | — | Socket pin | | ✓ |
| 8 | C_OSCM | 0 | 270pF 25V | — | — | Leaded capacitor | 2.54mm pitch | ✓ |
| 9 | C_OSCM | 1 | 270pF 25V | — | — | Chip capacitor | 3.2mm×1.6mm | |
| 10 | C_OAP | 0 | Not mount | — | — | Chip capacitor | 3.2mm×1.6mm | ✓ |
| 11 | C_OAM | 0 | Not mount | — | — | Chip capacitor | 3.2mm×1.6mm | ✓ |
| 12 | C_OBM | 0 | Not mount | — | — | Chip capacitor | 3.2mm×1.6mm | ✓ |
| 13 | C_OBP | 0 | Not mount | — | — | Chip capacitor | 3.2mm×1.6mm | ✓ |
| 14 | CON1 | 1 | Connector | — | — | Connector 4P 2.5 | | |
| 15 | CON2 | 0 | Connector | — | — | Connector 2P 2.5 | | ✓ |
| 16 | CON3 | 0 | Connector | — | — | Connector 2P 2.5 | | ✓ |
| 17 | CON4 | 1 | Connector | — | — | Connector 3P 2.5 | | |
| 18 | CON5 | 1 | Connector | — | — | Connector 3P 2.5 | | |
| 19 | OUT_A- | 1 | Check terminal | — | — | Check pin | | |
| 20 | OUT_A+ | 1 | Check terminal | — | — | Check pin | | |
| 21 | OUT_B- | 1 | Check terminal | — | — | Check pin | | |
| 22 | OUT_B+ | 1 | Check terminal | — | — | Check pin | | |
| 23 | RSA | 1 | Check terminal | — | — | Check pin | | |
| 24 | RSB | 1 | Check terminal | — | — | Check pin | | |
| 25 | VCC | 1 | Check terminal | — | — | Check pin | | |

| | | | | | | | | |
|----|---------|---|----------------|---|---|-----------------|--------------|---|
| 26 | VDD | 1 | Check terminal | — | — | Check pin | | |
| 27 | VM | 1 | Check terminal | — | — | Check pin | | |
| 28 | L_OUT | 1 | Check terminal | — | — | Check pin | | |
| 29 | C_OUT | 1 | Check terminal | — | — | Check pin | | |
| 30 | D_OUT | 1 | Check terminal | — | — | Check pin | | |
| 31 | VREFB | 1 | Check terminal | — | — | Check pin | | |
| 32 | VREFA | 1 | Check terminal | — | — | Check pin | | |
| 33 | OSCM | 1 | Check terminal | — | — | Check pin | | |
| 34 | NC | 0 | Check terminal | — | — | Check pin | | ✓ |
| 35 | SI | 1 | Check terminal | — | — | Check pin | | |
| 36 | SCK | 1 | Check terminal | — | — | Check pin | | |
| 37 | DATA | 1 | Check terminal | — | — | Check pin | | |
| 38 | SCLR- | 1 | Check terminal | — | — | Check pin | | |
| 39 | G- | 1 | Check terminal | — | — | Check pin | | |
| 40 | STANDBY | 1 | Check terminal | — | — | Check pin | | |
| 41 | GND1 | 1 | Check terminal | — | — | Check pin | | |
| 42 | GND2 | 1 | Check terminal | — | — | Check pin | | |
| 43 | GND3 | 1 | Check terminal | — | — | Check pin | | |
| 44 | GND4 | 1 | Check terminal | — | — | Check pin | | |
| 45 | GND5 | 1 | Check terminal | — | — | Check pin | | |
| 46 | GND6 | 1 | Check terminal | — | — | Check pin | | |
| 47 | GND7 | 1 | Check terminal | — | — | Check pin | | |
| 48 | JP_VRF1 | 1 | Pin header 2P | — | — | Jumper | | |
| 49 | JP_VRF1 | 1 | Jump socket | — | — | Short pin | | |
| 50 | JP_VRF2 | 1 | Pin header 2P | — | — | Jumper | | |
| 51 | JP_VRF2 | 1 | Jump socket | — | — | Short pin | | |
| 52 | JP_VCC | 1 | Pin header 2P | — | — | Jumper | | |
| 53 | JP_VCC | 1 | Jump socket | — | — | Short pin | | |
| 54 | R_ID | 1 | 100kΩ 0.25W | — | — | Leaded resistor | 2.54mm pitch | |
| 55 | R_MOUT | 1 | 100kΩ 0.25W | — | — | Leaded resistor | 2.54mm pitch | |
| 56 | R_LOUT | 1 | 100kΩ 0.25W | — | — | Leaded resistor | 2.54mm pitch | |
| 57 | R_OSCM | 0 | Socket pin | — | — | Socket pin | | ✓ |

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